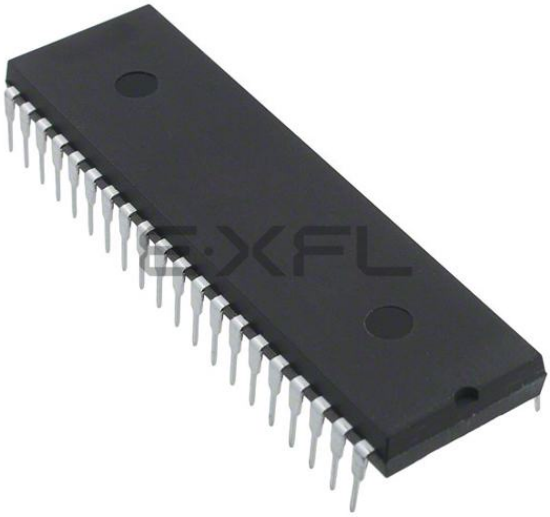

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	768 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Through Hole
Package / Case	40-DIP (0.600", 15.24mm)
Supplier Device Package	40-PDIL
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c51rd2-lca

4. SFR Mapping

The Special Function Registers (SFRs) of the TS80C51Rx2 fall into the following categories:

- C51 core registers: ACC, B, DPH, DPL, PSW, SP, AUXR1
- I/O port registers: P0, P1, P2, P3, P4, P5
- Timer registers: T2CON, T2MOD, TCON, TH0, TH1, TH2, TMOD, TL0, TL1, TL2, RCAP2L, RCAP2H
- Serial I/O port registers: SADDR, SADEN, SBUF, SCON
- Power and clock control registers: PCON
- HDW Watchdog Timer Reset: WDTRST, WDTPRG
- PCA registers: CL, CH, CCAPiL, CCAPiH, CCON, CMOD, CCAPMi
- Interrupt system registers: IE, IP, IPH
- Others: AUXR, CKCON

Table 1. All SFRs with their address and their reset value

	Bit addressable	**Non Bit addressable**							
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	
F8h		CH 0000 0000	CCAP0H XXXX XXXX	CCAP1H XXXX XXXX	CCAPL2H XXXX XXXX	CCAPL3H XXXX XXXX	CCAPL4H XXXX XXXX		FFh
F0h	B 0000 0000								F7h
E8h	P5 bit addressable 1111 1111	CL 0000 0000	CCAP0L XXXX XXXX	CCAP1L XXXX XXXX	CCAPL2L XXXX XXXX	CCAPL3L XXXX XXXX	CCAPL4L XXXX XXXX		EFh
E0h	ACC 0000 0000								E7h
D8h	CCON 00X0 0000	CMOD 00XX X000	CCAPM0 X000 0000	CCAPM1 X000 0000	CCAPM2 X000 0000	CCAPM3 X000 0000	CCAPM4 X000 0000		DFh
D0h	PSW 0000 0000								D7h
C8h	T2CON 0000 0000	T2MOD XXXX XX00	RCAP2L 0000 0000	RCAP2H 0000 0000	TL2 0000 0000	TH2 0000 0000			CFh
C0h	P4 bit addressable 1111 1111							P5 byte addressable 1111 1111	C7h
B8h	IP X000 000	SADEN 0000 0000							BFh
B0h	P3 1111 1111							IPH X000 0000	B7h
A8h	IE 0000 0000	SADDR 0000 0000							AFh
A0h	P2 1111 1111		AUXR1 XXXX0XX0				WDTRST XXXX XXXX	WDTPRG XXXX X000	A7h
98h	SCON 0000 0000	SBUF XXXX XXXX							9Fh
90h	P1 1111 1111								97h
88h	TCON 0000 0000	TMOD 0000 0000	TL0 0000 0000	TL1 0000 0000	TH0 0000 0000	TH1 0000 0000	AUXR XXXXXX00	CKCON XXXX XXX0	8Fh
80h	P0 1111 1111	SP 0000 0111	DPL 0000 0000	DPH 0000 0000				PCON 00X1 0000	87h
	0/8	1/9	2/A	3/B	4/C	5/D	6/E	7/F	

reserved

Mnemonic	Pin Number			Type	Name And Function
	DIL	LCC	VQFP 1.4		
V_{SS}	20	22	16	I	**Ground:** 0V reference
Vss1		1	39	I	**Optional Ground:** Contact the Sales Office for ground connection.
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	**Port 0**: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs. Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	**Port 1:** Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
	3	4	42	I	**ECI (P1.2):** External Clock for the PCA
	4	5	43	I/O	**CEX0 (P1.3):** Capture/Compare External I/O for PCA module 0
	5	6	44	I/O	**CEX1 (P1.4):** Capture/Compare External I/O for PCA module 1
	6	7	45	I/O	**CEX0 (P1.5):** Capture/Compare External I/O for PCA module 2
	7	8	46	I/O	**CEX0 (P1.6):** Capture/Compare External I/O for PCA module 3
	8	9	47	I/O	**CEX0 (P1.7):** Capture/Compare External I/O for PCA module 4
P2.0-P2.7	21-28	24-31	18-25	I/O	**Port 2**: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @DPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), port 2 emits the contents of the P2 SFR. Some Port 2 pins (P2.0 to P2.5) receive the high order address bits during EPROM programming and verification:
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	**Port 3:** Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Some Port 3 pins (P3.4 to P3.5) receive the high order address bits during EPROM programming and verification. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	**RXD (P3.0):** Serial input port
	11	13	7	O	**TXD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt 0
	13	15	9	I	**$\overline{\text{INT1}}$ (P3.3):** External interrupt 1
	14	16	10	I	**T0 (P3.4):** Timer 0 external input
	15	17	11	I	**T1 (P3.5):** Timer 1 external input
	16	18	12	O	**$\overline{\text{WR}}$ (P3.6):** External data memory write strobe
	17	19	13	O	**$\overline{\text{RD}}$ (P3.7):** External data memory read strobe

Reset	9	10	4	I	**Reset:** A high on this pin for two machine cycles while the oscillator is running, resets the device. An internal diffused resistor to V_{SS} permits a power-on reset using only an external capacitor to $V_{CC.}$ If the hardware watchdog reaches its time-out, the reset pin becomes an output during the time the internal reset is activated.

	PLCC68	SQUARE VQFP64 1.4
P3.2	40	29
P3.3	41	30
P3.4	42	31
P3.5	43	32
P3.6	45	34
P3.7	47	36
RESET	30	21
ALE/$\overline{PROG}$	68	56
$\overline{PSEN}$	67	55
$\overline{EA}$/VPP	2	58
XTAL1	49	38
XTAL2	48	37
P4.0	20	11
P4.1	24	15
P4.2	26	17
P4.3	44	33
P4.4	46	35
P4.5	50	39
P4.6	53	42
P4.7	57	46
P5.0	60	49
P5.1	62	51
P5.2	63	52
P5.3	7	62
P5.4	8	63
P5.5	10	1
P5.6	13	4
P5.7	16	7

6. TS80C51Rx2 Enhanced Features

In comparison to the original 80C52, the TS80C51Rx2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The extended RAM.
- The Programmable Counter Array (PCA).
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

6.1. X2 Feature

The TS80C51Rx2 core needs only 6 clock periods per machine cycle. This feature called ”X2” provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

6.1.1. Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 1. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 2. shows the mode switching waveforms.

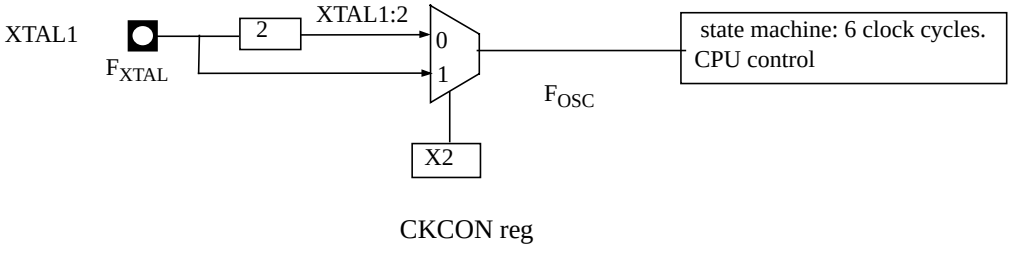

Figure 1. Clock Generation Diagram

6.2. Dual Data Pointer Register Ddptr

The additional data pointer can be used to speed up code execution and reduce code size in a number of ways.

The dual DPTR structure is a way by which the chip will specify the address of an external data memory location. There are two 16-bit DPTR registers that address the external memory, and a single bit called DPS = AUXR1/bit0 (See Table 4.) that allows the program code to switch between them (Refer to Figure 3).

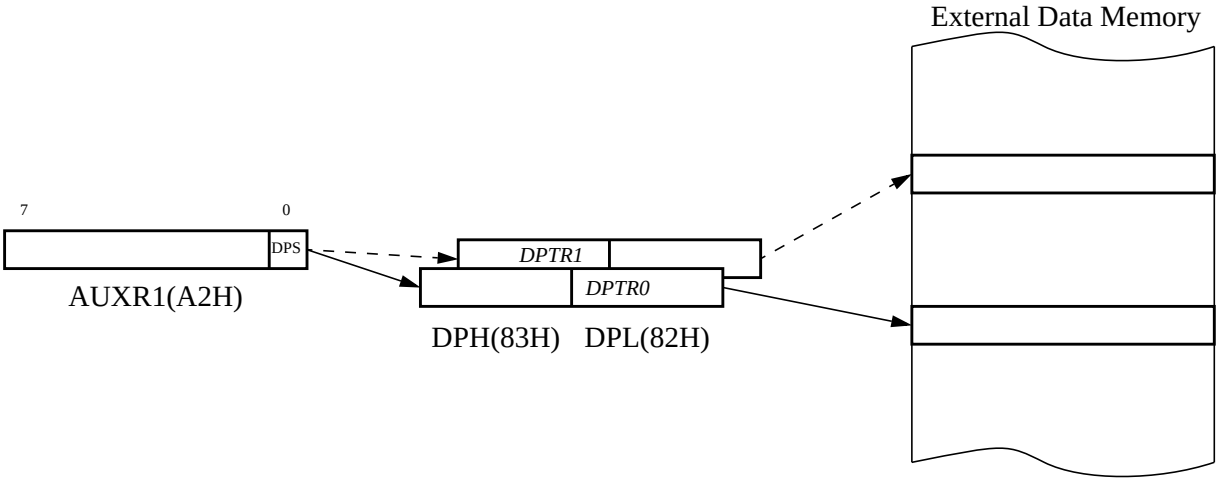

Figure 3. Use of Dual Pointer

Table 4. AUXR1: Auxiliary Register 1

AUXR1 Address 0A2H		-	-	-	-	GF3	-	-	DPS
	Reset value	X	X	X	X	0	X	X	0

Symbol	Function	
-	Not implemented, reserved for future use.[a]	
DPS	Data Pointer Selection.	
	DPS	**Operating Mode**
	0	DPTR0 Selected
	1	DPTR1 Selected
GF3	This bit is a general purpose user flag[b].	

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.
b. GF3 will not be available on first version of the RC devices.

Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

6.3. Expanded RAM (XRAM)

The TS80C51Rx2 provide additional Bytes of ramdom access memory (RAM) space for increased data parameter handling and high level language usage.

RA2, RB2 and RC2 devices have 256 bytes of expanded RAM, from 00H to FFH in external data space; RD2 devices have 768 bytes of expanded RAM, from 00H to 2FFH in external data space.

The TS80C51Rx2 has internal data memory that is mapped into four separate segments.

The four segments are:

- 1. The Lower 128 bytes of RAM (addresses 00H to 7FH) are directly and indirectly addressable.
- 2. The Upper 128 bytes of RAM (addresses 80H to FFH) are indirectly addressable only.
- 3. The Special Function Registers, SFRs, (addresses 80H to FFH) are directly addressable only.
- 4. The expanded RAM bytes are indirectly accessed by MOVX instructions, and with the EXTRAM bit cleared in the AUXR register. (See Table 5.)

The Lower 128 bytes can be accessed by either direct or indirect addressing. The Upper 128 bytes can be accessed by indirect addressing only. The Upper 128 bytes occupy the same address space as the SFR. That means they have the same address, but are physically separate from SFR space.

When an instruction accesses an internal location above address 7FH, the CPU knows whether the access is to the upper 128 bytes of data RAM or to SFR space by the addressing mode used in the instruction.

- Instructions that use direct addressing access SFR space. **For example: MOV 0A0H, # data** ,accesses the SFR at location 0A0H (which is P2).
- Instructions that use indirect addressing access the Upper 128 bytes of data RAM. **For example: MOV @R0, # data** where R0 contains 0A0H, accesses the data byte at address 0A0H, rather than P2 (whose address is 0A0H).
- The 256 or 768 XRAM bytes can be accessed by indirect addressing, with EXTRAM bit cleared and MOVX instructions. This part of memory which is physically located on-chip, logically occupies the first 256 or 768 bytes of external data memory.
- With EXTRAM = 0, the XRAM is indirectly addressed, using the MOVX instruction in combination with any of the registers R0, R1 of the selected bank or DPTR. **An access to XRAM will not affect ports P0, P2, P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$)**. **For example, with EXTRAM = 0, MOVX @R0, # data** where R0 contains 0A0H, accesses the XRAM at address 0A0H rather than external memory. An access to external data memory locations higher than FFH (i.e. 0100H to FFFFH) (higher than 2FFH (i.e. 0300H to FFFFH for RD devices) will be performed with the MOVX DPTR instructions in the same way as in the standard 80C51, so with P0 and P2 as data/address busses, and P3.6 and P3.7 as write and read timing signals. Refer to Figure . For RD devices, accesses to expanded RAM from 100H to 2FFH can only be done thanks to the use of DPTR.
- With EXTRAM = 1, MOVX @Ri and MOVX @DPTR will be similar to the standard 80C51. MOVX @ Ri will provide an eight-bit address multiplexed with data on Port0 and any output port pins can be used to output higher order address bits. This is to provide the external paging capability. MOVX @DPTR will generate a sixteen-bit address. Port2 outputs the high-order eight address bits (the contents of DPH) while Port0 multiplexes the low-order eight address bits (DPL) with data. MOVX @ Ri and MOVX @DPTR will generate either read or write signals on P3.6 ($\overline{WR}$) and P3.7 ($\overline{RD}$).

The stack pointer (SP) may be located anywhere in the 256 bytes RAM (lower and upper RAM) internal data memory. The stack may not be located in the XRAM.

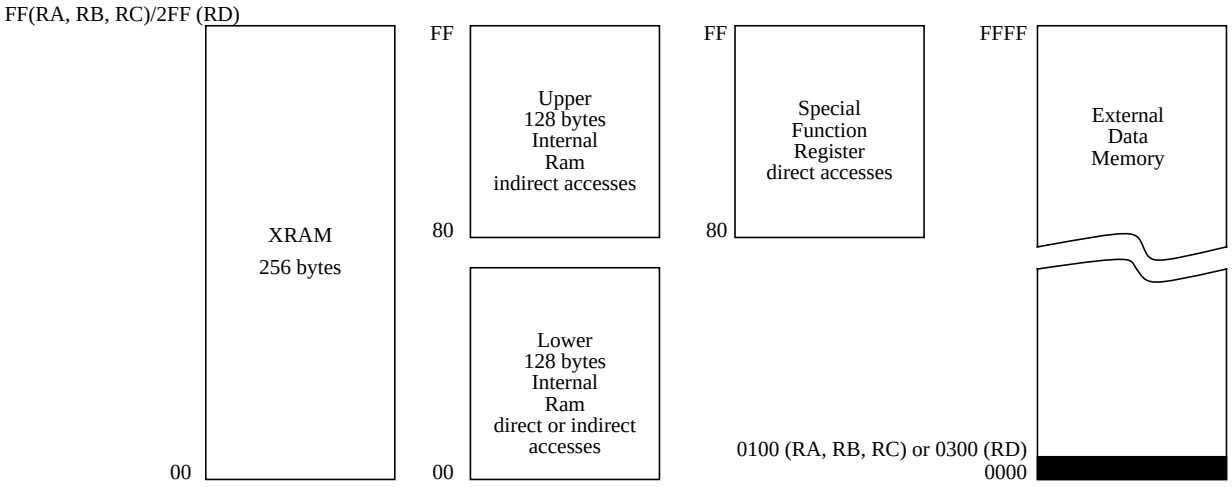

Figure 4. Internal and External Data Memory Address

Table 5. Auxiliary Register AUXR

AUXR Address 08EH	-	-	-	-	-	-	EXTRAM	AO
Reset value	X	X	X	X	X	X	0	0

Symbol	Function	
-	Not implemented, reserved for future use.[a]	
AO	Disable/Enable ALE	
	AO	**Operating Mode**
	0	ALE is emitted at a constant rate of 1/6 the oscillator frequency (or 1/3 if X2 mode is used)
	1	ALE is active only during a MOVX or MOVC instruction
EXTRAM	Internal/External RAM (00H-FFH) access using MOVX @ Ri/ @ DPTR	
	EXTRAM	**Operating Mode**
	0	Internal XRAM access using MOVX @ Ri/ @ DPTR
	1	External data memory access

a. User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

6.7. Interrupt System

The TS80C51Rx2 has a total of 7 interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), three timer interrupts (timers 0, 1 and 2), the serial port interrupt and the PCA global interrupt. These interrupts are shown in Figure 16.

WARNING: Note that in the first version of RC devices, the PCA interrupt is in the lowest priority. Thus the order in $\overline{INT0}$, TF0, $\overline{INT1}$, TF1, RI or TI, TF2 or EXF2, PCA.

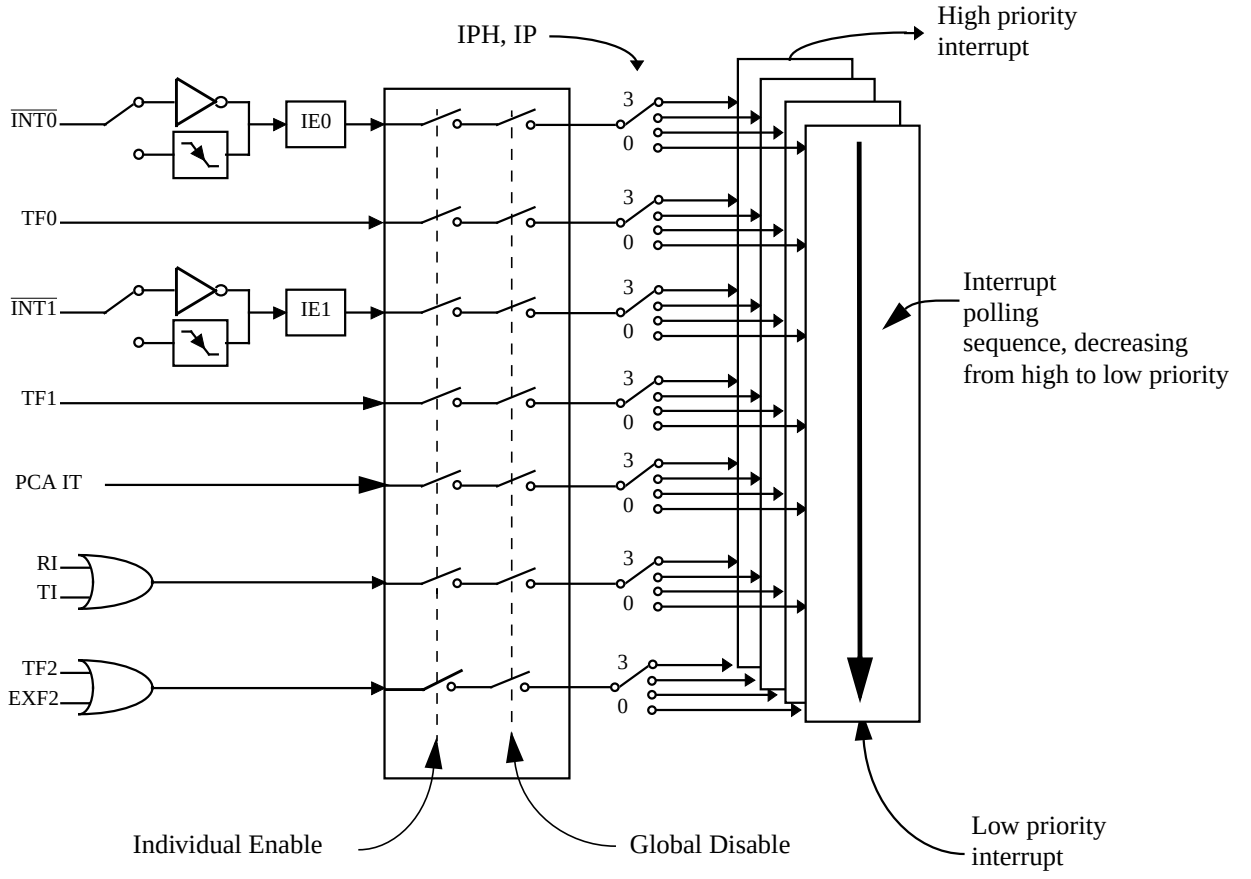

Figure 16. Interrupt Control System

Each of the interrupt sources can be individually enabled or disabled by setting or clearing a bit in the Interrupt Enable register (See Table 19.). This register also contains a global disable bit, which must be cleared to disable all interrupts at once.

Each interrupt source can also be individually programmed to one out of four priority levels by setting or clearing a bit in the Interrupt Priority register (See Table 20.) and in the Interrupt Priority High register (See Table 21.). shows the bit values and priority levels associated with each combination.

The PCA interrupt vector is located at address 0033H. All other vector addresses are the same as standard C52 devices.

6.8. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

6.9. Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 17., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 17. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C51Rx2 into power-down mode.

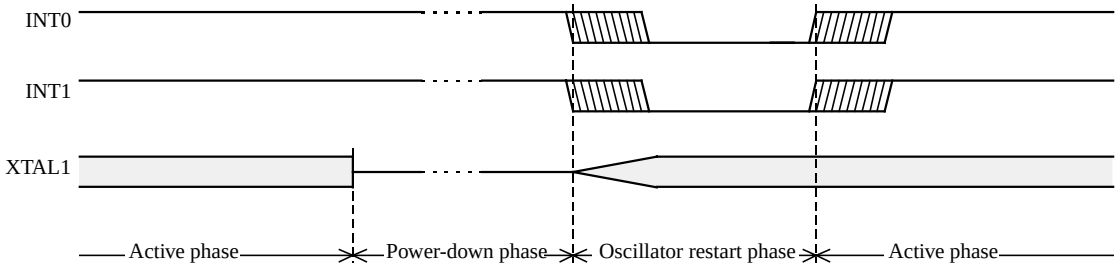

Figure 17. Power-Down Exit Waveform

Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.
NOTE: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Table 22. The state of ports during idle and power-down mode

Mode	Program Memory	ALE	$\overline{\text{PSEN}}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data*	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data*	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

* Port 0 can force a "zero" level. A "one" will leave port floating.

6.10. Hardware Watchdog Timer

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upset. The WDT consists of a 14-bit counter and the WatchDog Timer ReSeT (WDTRST) SFR. The WDT is by default disabled from exiting reset. To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, it will increment every machine cycle while the oscillator is running and there is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST-pin.

6.10.1. Using the WDT

To enable the WDT, user must write 01EH and 0E1H in sequence to the WDTRST, SFR location 0A6H. When WDT is enabled, the user needs to service it by writing to 01EH and 0E1H to WDTRST to avoid WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH) and this will reset the device. When WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycle. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST-pin. The RESET pulse duration is 96 x T_{OSC} , where $T_{OSC} = 1/F_{OSC}$. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

To have a more powerful WDT, a 2^7 counter has been added to extend the Time-out capability, ranking from 16ms to 2s @ F_{OSC} = 12MHz. To manage this feature, refer to WDTPRG register description, Table 24. (SFR0A7h).

Table 23. WDTRST Register

WDTRST Address (0A6h)

	7	6	5	4	3	2	1
Reset value	X	X	X	X	X	X	X

Write only, this SFR is used to reset/enable the WDT by writing 01EH then 0E1H in sequence.

6.11. ONCE™ Mode (ON Chip Emulation)

The ONCE mode facilitates testing and debugging of systems using TS80C51Rx2 without removing the circuit from the board. The ONCE mode is invoked by driving certain pins of the TS80C51Rx2; the following sequence must be exercised:

- Pull ALE low while the device is in reset (RST high) and $\overline{PSEN}$ is high.
- Hold ALE low as RST is deactivated.

While the TS80C51Rx2 is in ONCE mode, an emulator or test CPU can be used to drive the circuit Table 26. shows the status of the port pins during ONCE mode.

Normal operation is restored when normal reset is applied.

Table 25. External Pin Status during ONCE Mode

ALE	PSEN	Port 0	Port 1	Port 2	Port 3	XTAL1/2
Weak pull-up	Weak pull-up	Float	Weak pull-up	Weak pull-up	Weak pull-up	Active

8. TS87C51RB2/RC2/RD2 EPROM

8.1. EPROM Structure

The TS87C51RB2/RC2/RD2 EPROM is divided in two different arrays:

- the code array: . . . . . 16/32/64 Kbytes.
- the encryption array: . . . . . 64 bytes.

In addition a third non programmable array is implemented:

- the signature array: . . . . . 4 bytes.

8.2. EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

8.2.1. Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

8.2.2. Program Lock Bits

The three lock bits, when programmed according to Table 29.8.2.3. , will provide different level of protection for the on-chip code and data.

Table 29. Program Lock bits

Program Lock Bits				Protection description
Security level	LB1	LB2	LB3	
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	P	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	P	U	Same as 2, also verify is disabled.
4	U	U	P	Same as 3, also external execution is disabled.

U: unprogrammed,
P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.

8.2.3. Signature bytes

The TS87C51RB2/RC2/RD2 contains 4 factory programmed signatures bytes. To read these bytes, perform the process described in section 8.3.

10. Electrical Characteristics

10.1. Absolute Maximum Ratings (1)

Ambiant Temperature Under Bias:	
C = commercial	0°C to 70°C
I = industrial	-40°C to 85°C
Storage Temperature	-65°C to + 150°C
Voltage on V_{CC} to V_{SS}	-0.5 V to + 7 V
Voltage on V_{PP} to V_{SS}	-0.5 V to + 13 V
Voltage on Any Pin to V_{SS}	-0.5 V to V_{CC} + 0.5 V
Power Dissipation	1 W(2)

NOTES

1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

10.2. Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel Wireless & Microcontrollers new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel Wireless & Microcontrollers presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			3 + 0.6 Freq (MHz) @12MHz 10.2 @16MHz 12.6	mA	V_{CC} = 5.5 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.25+0.3 Freq (MHz) @12MHz 3.9 @16MHz 5.1	mA	V_{CC} = 5.5 V(2)

10.4. DC Parameters for Low Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5 V ± 10%; F = 0 to 30 MHz.

Table 33. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3, 4, 5 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3, 4, 5	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2, 3, 4, 5			-50	µA	Vin = 0.45 V
I_{LI}	Input Leakage Current			±10	µA	0.45 V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3, 4, 5			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5 V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) @12MHz 3.4 @16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) @12MHz 4.6 @16MHz 5.8	mA	V_{CC} = 3.3 V(8)

Table 38. AC Parameters for a Variable Clock: derating formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T_{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T_{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T_{PXIX}	Min	x	x	0	0	0	ns
T_{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T_{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T_{PLAZ}	Max	x	x	10	10	10	ns

10.5.3. External Program Memory Read Cycle

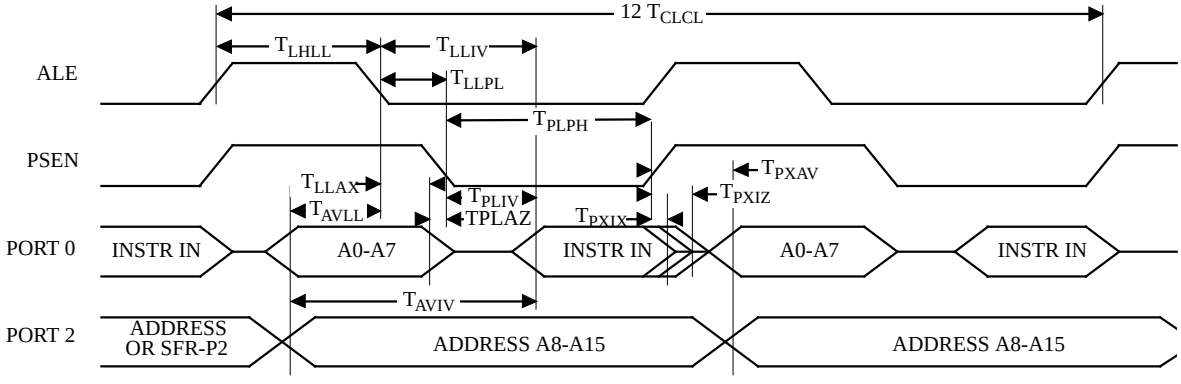

Figure 25. External Program Memory Read Cycle

10.5.6. External Data Memory Read Cycle

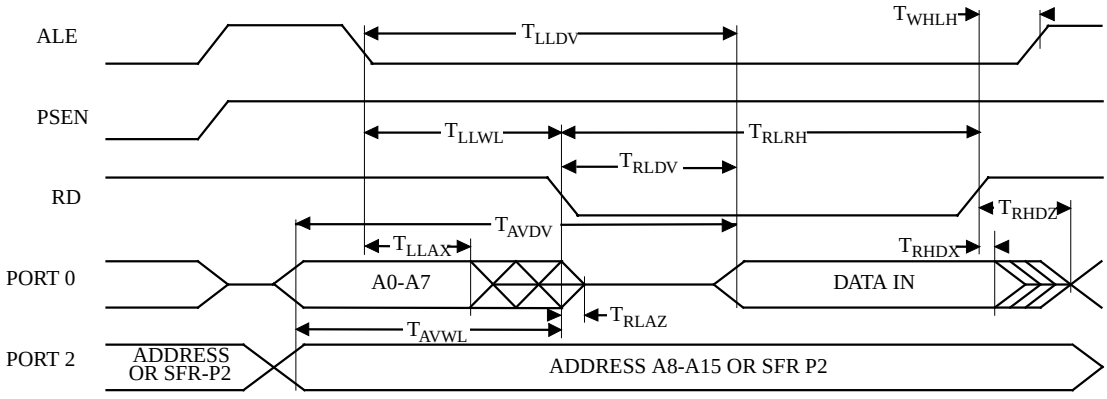

Figure 27. External Data Memory Read Cycle

10.5.7. Serial Port Timing - Shift Register Mode

Table 42. Symbol Description

Symbol	Parameter
T_{XLXL}	Serial port clock cycle time
T_{QVHX}	Output data set-up to clock rising edge
T_{XHQX}	Output data hold after clock rising edge
T_{XHDX}	Input data hold after clock rising edge
T_{XHDV}	Clock rising edge to input data valid

Table 43. AC Parameters for a Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T_{XLXL}	300		200		300		300		400		ns
T_{QVHX}	200		117		200		200		283		ns
T_{XHQX}	30		13		30		30		47		ns
T_{XHDX}	0		0		0		0		0		ns
T_{XHDV}		117		34		117		117		200	ns

10.5.11. External Clock Drive Characteristics (XTAL1)

Table 46. AC Parameters

Symbol	Parameter	Min	Max	Units
T_{CLCL}	Oscillator Period	25		ns
T_{CHCX}	High Time	5		ns
T_{CLCX}	Low Time	5		ns
T_{CLCH}	Rise Time		5	ns
T_{CHCL}	Fall Time		5	ns
T_{CHCX}/T_{CLCX}	Cyclic ratio in X2 mode	40	60	%

10.5.12. External Clock Drive Waveforms

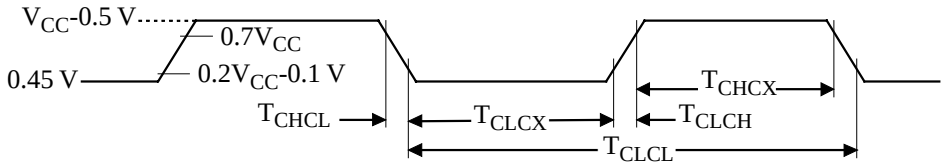

Figure 30. External Clock Drive Waveforms

10.5.13. AC Testing Input/Output Waveforms

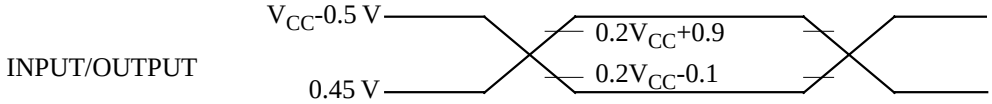

Figure 31. AC Testing Input/Output Waveforms

AC inputs during testing are driven at V_{CC} - 0.5 for a logic “1” and 0.45V for a logic “0”. Timing measurement are made at V_{IH} min for a logic “1” and V_{IL} max for a logic “0”.

10.5.14. Float Waveforms

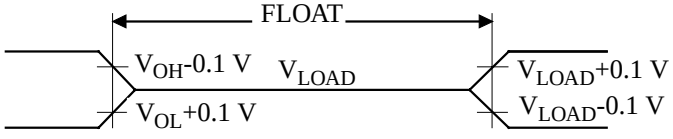

Figure 32. Float Waveforms

Table 48. Possible Ordering Entries

	TS80C51RA2/RD2 ROMless	TS83C51RB2/RC2/RD2zzz ROM	TS87C51RB2/RC2/RD2 OTP
-MCA	X	X	X
-MCB	X	X	X
-MCE	X	X	X
-MCL	RD2 only	RD2 only	RD2 only
-MCM	RD2 only	RD2 only	RD2 only
-VCA	X	X	X
-VCB	X	X	X
-VCE	X	X	X
-VCL	RD2 only	RD2 only	RD2 only
-VCM	RD2 only	RD2 only	RD2 only
-LCA	X	X	X
-LCB	X	X	X
-LCE	X	X	X
-LCL	RD2 only	RD2 only	RD2 only
-LCM	RD2 only	RD2 only	RD2 only
-MIA	X	X	X
-MIB	X	X	X
-MIE	X	X	X
-MIL	RD2 only	RD2 only	RD2 only
-MIM	RD2 only	RD2 only	RD2 only
-VIA	X	X	X
-VIB	X	X	X
-VIE	X	X	X
-VIL	RD2 only	RD2 only	RD2 only
-VIM	RD2 only	RD2 only	RD2 only
-LIA	X	X	X
-LIB	X	X	X
-LIE	X	X	X
-LIL	RD2 only	RD2 only	RD2 only
-LIM	RD2 only	RD2 only	RD2 only
-EA	X		X
-EB	X		X
-EE	X		X
-EL	RD2 only		RD2 only
-EM	RD2 only		RD2 only
-EJ			RC2 and RD2 only
-EK			RC2 and RD2 only
-EN			RD2 only

- -Ex for samples
- Tape and Reel available for B, E, L and M packages
- Dry pack mandatory for E and M packages